

CLAIMS

1. An epoxy resin composition for encapsulating of semiconductors which comprises (A) an epoxy resin, (B) a phenolic resin, (C) a curing accelerator and (D) an inorganic filler as main components, characterized in that properties of a cured product formed by heating and curing the epoxy resin composition satisfy expressions, $a \geq 10^R$ ($R=10 \times (b+c)-1$), $300 \leq a \leq 20000$ and $0.15 \leq b+c \leq 0.50$ in which a denotes a flexural modulus (N/mm^2) at molding temperature, b denotes a cure shrinkage (%) and c denotes a heat shrinkage (%) of from molding temperature to room temperature.

2. An epoxy resin composition for encapsulating of semiconductors according to claim 1, wherein the cured product has a moisture absorption rate of not more than 0.20% by weight after treated for 168 hours in an environment of 85°C and 60% in relative humidity.

3. ~~An epoxy resin composition for encapsulating of semiconductors according to claim 1 or 2, wherein the epoxy resin and/or the phenolic resin have/has a naphthalene skeleton.~~

4. A semiconductor device obtained by encapsulating with the epoxy resin composition according to claim 1, 2 or

3.

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Sub
a1

Add
a2